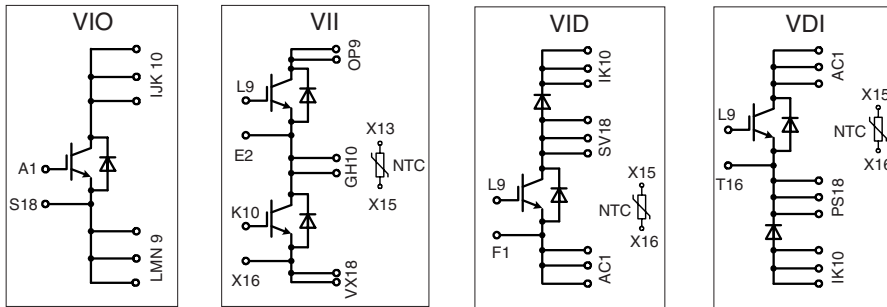


# IGBT Modules in ECO-PAC 2

Short Circuit SOA Capability  
 Square RBSOA

$I_{C25} = 121 \text{ A}$   
 $V_{CES} = 600 \text{ V}$   
 $V_{CE(sat) \text{ typ.}} = 2.3 \text{ V}$

Preliminary data sheet



Pin arrangement see outlines

IGBTs				
Symbol	Conditions	Maximum Ratings		
$V_{CES}$	$T_{VJ} = 25^{\circ}\text{C to } 150^{\circ}\text{C}$	600 V		
$V_{GES}$		$\pm 20$ V		
$I_{C25}$	$T_C = 25^{\circ}\text{C}$	121 A		
$I_{C80}$	$T_C = 80^{\circ}\text{C}$	83 A		
$I_{CM}$	$V_{GE} = \pm 15 \text{ V}; R_G = 2.2 \Omega; T_{VJ} = 125^{\circ}\text{C}$ RBSOA, Clamped inductive load; $L = 100 \mu\text{H}$	200 A		
$V_{CEK}$		360 V		
$t_{SC}$ (SCSOA)	$V_{CE} = V_{CES}; V_{GE} = \pm 15 \text{ V}; R_G = 2.2 \Omega; T_{VJ} = 125^{\circ}\text{C}$ non-repetitive	10 $\mu\text{s}$		
$P_{tot}$	$T_C = 25^{\circ}\text{C}$	379 W		
Symbol	Conditions	Characteristic Values ( $T_{VJ} = 25^{\circ}\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_{CE(sat)}$	$I_C = 130 \text{ A}; V_{GE} = 15 \text{ V}; T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$		2.3	2.9 V
				2.6
$V_{GE(th)}$	$I_C = 1.5 \text{ mA}; V_{GE} = V_{CE}$	4.5		6.5 V
$I_{CES}$	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}; T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$			1.2 mA 7.5 mA
$I_{GES}$	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$			400 nA
$t_{d(on)}$	Inductive load, $T_{VJ} = 125^{\circ}\text{C}$ $V_{CE} = 300 \text{ V}; I_C = 80 \text{ A}$ $V_{GE} = 15/0 \text{ V}; R_G = 2.2 \Omega$		25	ns
$t_r$			11	ns
$t_{d(off)}$			150	ns
$t_f$			30	ns
$E_{on}$			0.8	mJ
$E_{off}$			2.3	mJ
$C_{ies}$	$V_{CE} = 25 \text{ V}; V_{GE} = 0 \text{ V}; f = 1 \text{ MHz}$		4.2	nF
$R_{thJC}$	(per IGBT)		0.33	K/W
$R_{thJH}$	with heatsink compound ( $0.42 \text{ K/m.K}; 50 \mu\text{m}$ )	0.66		K/W

### Features

- NPT IGBT's
  - positive temperature coefficient of saturation voltage
  - fast switching
- FRED diodes
  - fast reverse recovery
  - low forward voltage
- Industry Standard Package
  - solderable pins for PCB mounting
  - isolated DCB ceramic base plate

### Advantages

- space and weight savings
- reduced protection circuits
- leads with expansion bend for stress relief

### Typical Applications

- AC and DC motor control
- AC servo and robot drives
- power supplies
- welding inverters

**Recommended replacement:**  
**Please contact your local sales office**

IXYS reserves the right to change limits, test conditions and dimensions.

### Reverse diodes (FRED)

Symbol	Conditions	Maximum Ratings	
$I_{F25}$	$T_C = 25^\circ\text{C}$	134.0	A
$I_{F80}$	$T_C = 80^\circ\text{C}$	82.3	A

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
$V_F$	$I_F = 80\text{ A}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.85	2.06	V
$I_{RM}$ $t_{rr}$	$I_F = 60\text{ A}; di/dt = 500\text{ A}/\mu\text{s}; T_{VJ} = 125^\circ\text{C}$ $V_R = 300\text{ V}; V_{GE} = 0\text{ V}$	28	100	A ns
$R_{thJC}$ $R_{thJH}$	with heatsink compound (0.42 K/m.K; 50 $\mu\text{m}$ )	0.66	1.32	K/W K/W

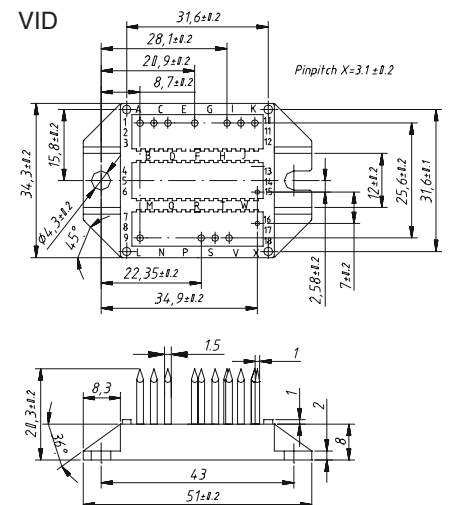
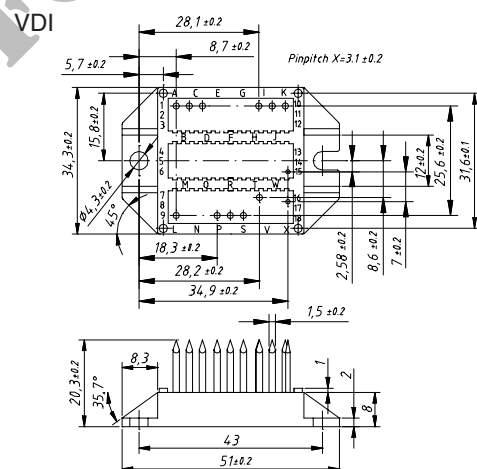
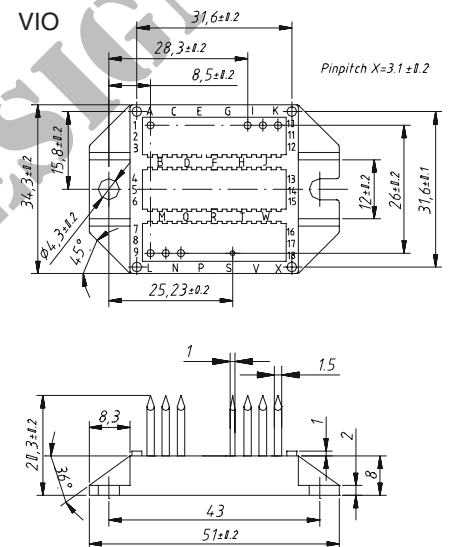
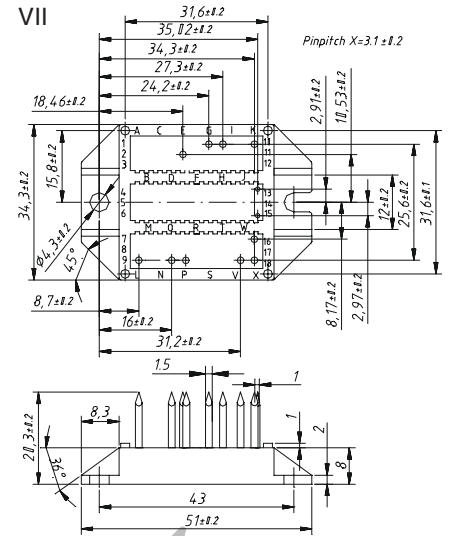
### Temperature Sensor NTC

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
$R_{25}$ $B_{25/50}$	$T = 25^\circ\text{C}$	4.75	5.0	5.25 k $\Omega$ K

### Module

Symbol	Conditions	Maximum Ratings	
$T_{VJ}$ $T_{stg}$		-40...+150	$^\circ\text{C}$ $^\circ\text{C}$
$V_{ISOL}$	$I_{ISOL} \leq 1\text{ mA}; 50/60\text{ Hz}$	3000	V~
$M_d$	mounting torque (M4)	1.5 - 2.0	Nm lb.in.
$a$	Max. allowable acceleration	50	$\text{m/s}^2$

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
$d_s$ $d_A$	Creepage distance on surface (Pin to heatsink) Strike distance in air (Pin to heatsink)	11.2		mm mm
Weight		24		g



Data according to IEC 60747 and refer to a single transistor or diode unless otherwise stated. IXYS reserves the right to change limits, test conditions and dimensions.